ABSTRACT

DIE PADDLE ENHANCEMENT FOR EXPOSED PAD IN SEMICONDUCTOR PACKAGING

A new design is provided for the die-paddle that is used as part of a package for packaging semiconductor devices. The new design of the invention creates a space between the ground ring of the die-paddle and the surface over which the ground paddle is mounted. The new design further comprises an S-shaped segment between the ground ring and the center of the die-paddle, the S-shaped segment provides stress relieve between the ground ring and the center of the die-paddle.

(FIGURE 4a IS SUGGESTED FOR PUBLICATION)